

COMPOSITION FOR INSULATING LAYER OF PRINTED WIRING BOARD

ABSTRACT

An object of the present invention is to provide a composition for use in an insulating layer of a printed wiring board, the composition having a low dielectric constant and a low dielectric loss tangent and having flame retardance. A resin composition for use in an insulating layer of a printed wiring board, the composition containing polybutadiene, wherein a molar ratio of a 1,2-bond structure and a 1,4-bond structure in the polybutadiene is 60:40 to 100:0, and a phosphorus-containing group of formula (III) is bound to one or more carbon atoms in the polybutadiene (in formula (III), * represents a binding position, X¹ and X² each independently represent a single bond or an oxygen atom, and R¹ and R² each independently represent an organic group.).

